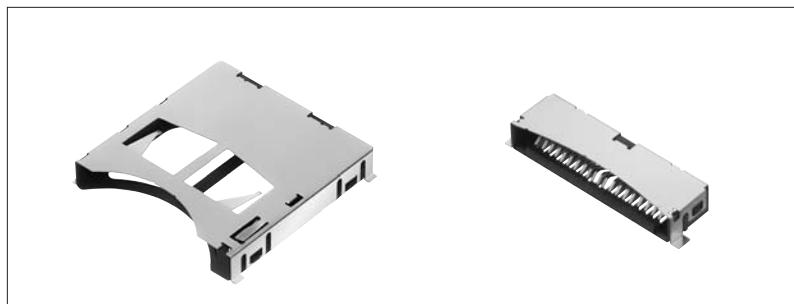


Connector for W-SIM

SCZA Series



High reliability contact structure best fit for portable devices.



Features

- Improved operability from long ejection stroke (5mm) and clear click feel.
- Good operational feel.
- Double contact-point for power and ground reduces risk of temporary power failure.
- Compact and low-profile suitable for portable devices.

Applications

- For mobile phones, PCs, and personal digital assistants

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
W-SIM

For
Memory
Stick Micro™

For
Memory
Stick™

Combine Type

For
Compact
Flash™

For PC cards
supporting
CardBus

For
Express
Card™

For CMOS
Camera Module

Typical Specifications

Items		Specifications
Structure	Applicable media	W-SIM
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Push-push type, Manual insertion/removal
Performance	Operating temperature range	-20℃ to +60℃
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	10,000cycles

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without boss L type	0	Tray	SCZA1A0100	1
		With boss L type			SCZA1A0200	2
		Without boss 0.6mm type			SCZA1A0300	3
		With boss 0.6mm type			SCZA1A0400	4
		Without boss 1.2mm type			SCZA1A0500	5
		With boss 1.2mm type			SCZA1A0600	6
Manual insertion/removal		With boss L type			SCZA2A0100	7
		Without boss 0.6mm type			SCZA2A0200	8

Unit:mm

For SD Memory Card
For microSD™ Card
For SIM Card 8pins
For W-SIM
For Memory Stick Micro™
For Memory Stick™
Combine Type
For Compact Flash™
For PC cards supporting CardBus
For Express Card™
For CMOS Camera Module

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
For SD Memory Card For microSD™ Card For SIM Card 8pins For W-SIM For Memory Stick Micro™ For Memory Stick™ Combine Type For Compact Flash™ For PC cards supporting CardBus	Push-push type Without boss 1.2mm type	
For Express Card™ For CMOS Camera Module	Push-push type With boss 1.2mm type	

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
7	Manual insertion/removal With boss L type	
8	Manual insertion/removal Without boss 0.6mm type	

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
W-SIM

For
Memory
Stick Micro™

For
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Combine Type

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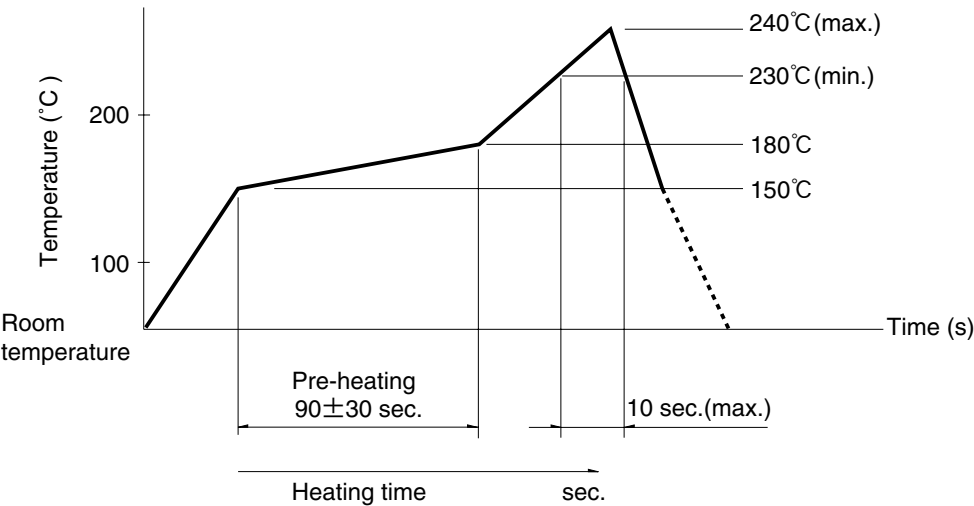
For
Express
Card™

For CMOS
Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) .
- 3. Temperature profile (Surface of products) .



Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.